Surface Mount Transient Voltage Suppressor Diode

Features

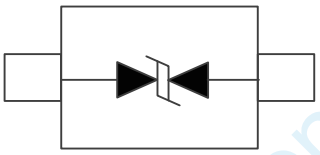
- ESD protection of one line
- Solid-state silicon-avalanche technology
- Working Voltage: 30.0V
- Peak Power up to 450 Watts @ 8 x 20μs Pulse
- Low Leakage current
- Low capacitance (Cj=24pF typ.)
- IEC 61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)

Applications

- Cellular Handsets & Accessories
- Portable devices
- Powerline
- Computer & Notebook

Mechanical Data

- UL Flame Rating : UL94V-0
- Reel Size : 7 inch
- RoHS/WEEE Compliant



Circuit Diagram



SOD323

Absolute Maximum Rating at T_A = 25 °C, unless otherwise specified

Rating	Symbol	Value	Units
Peak Pulse Power (t_p =8/20μs)	P_{PP}	450	Watts
Peak Pulse Current (t_p =8/20μs) (note1)	I_{pp}	9	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	±30 ±30	kV
Lead Soldering Temperature	T_L	260(10seconds)	℃
Junction Temperature	T_J	-55 to + 125	℃
Storage Temperature	T_{stg}	-55 to + 150	℃

OVREG Semiconductor (xi'an) Co.,Ltd.

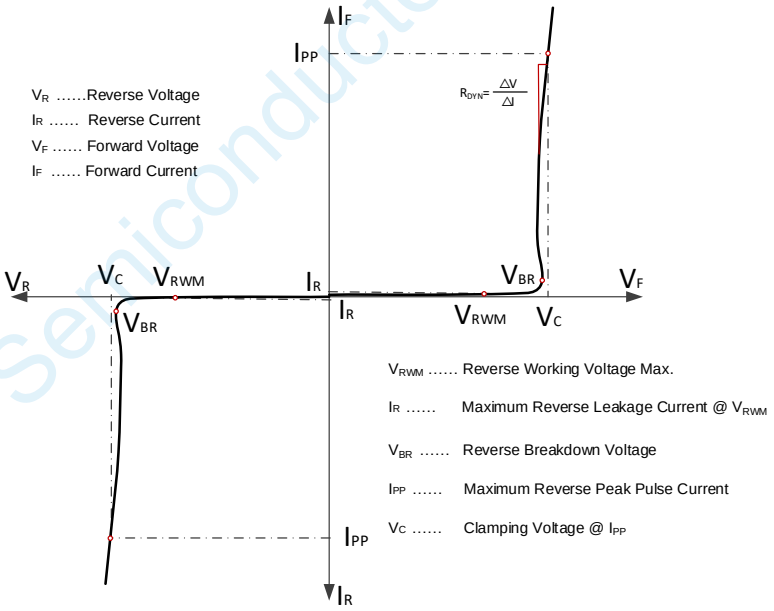
Electrical Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Min.	Typical	Max.	Units
Reverse Stand-Off Voltage	V_{RWM}				30.0	V
Reverse Breakdown Voltage	V_{BR}	I_T=1mA	35			V
Reverse Leakage Current	I_R	V_{RWM}=30.0V, T=25℃			0.5	μA
Peak Pulse Current	I_{PP}	tp =8/20μs			9	A
Clamping Voltage	V_C	I_{PP}=1A, tp=8/20μs		36		V
Clamping Voltage	V_C	I_{PP}=9A, tp=8/20μs		48	50	V
Junction Capacitance	C_J	V_R=0V,f=1MHz		24	28	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. All parameters specified at T_A = 25°C unless otherwise noted.
2. These parameters are guaranteed by design and characterization.
3. Standard IEC 61000−4−2 with $C_{Discharge}$ = 150 pF, $R_{Discharge}$ = 330 Ω

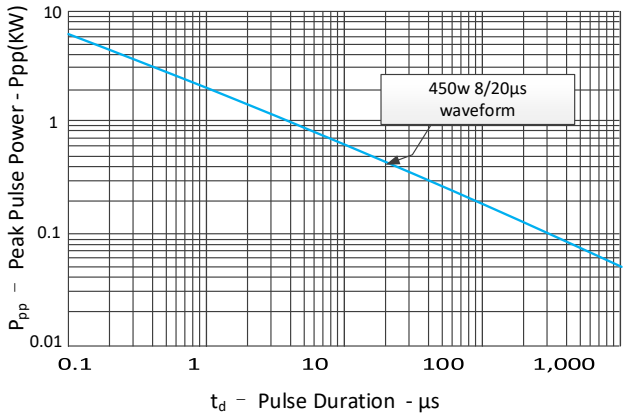
Electrical Parameters at T_A = 25 °C, unless otherwise specified



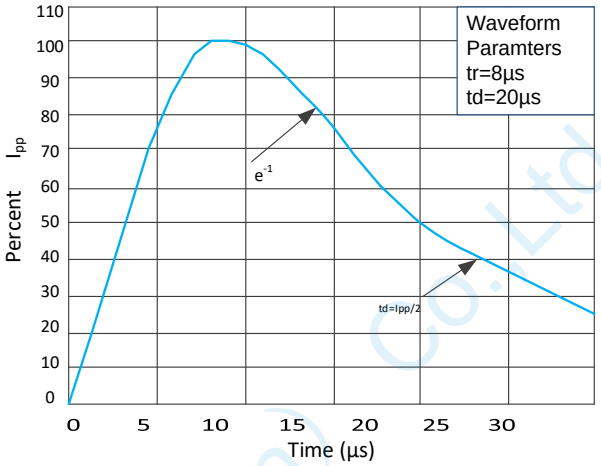
OVREG Semiconductor (xi'an) Co.,Ltd.

Typical Characteristics at T_A = 25 °C, unless otherwise specified

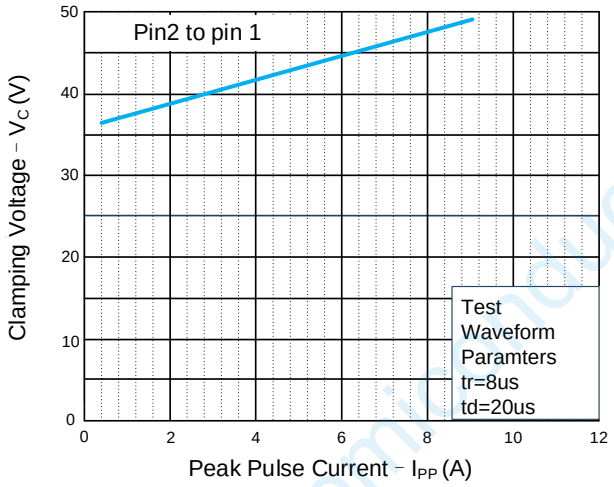
Peak Pulse Power vs. Pulse Time



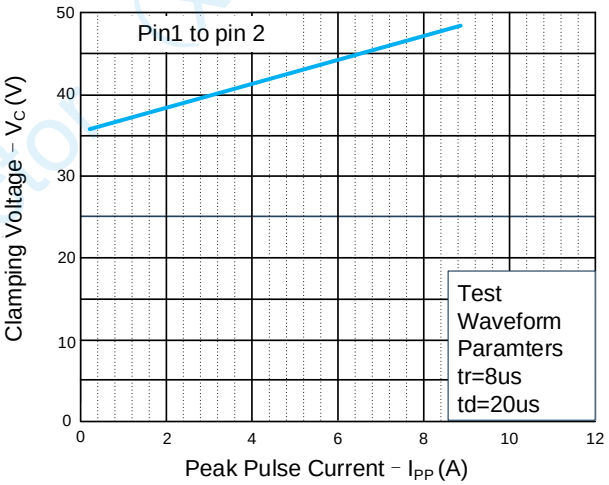
8/20uS Pulse Waveform



Forward Clamping Voltage vs. peak PulseCurrent

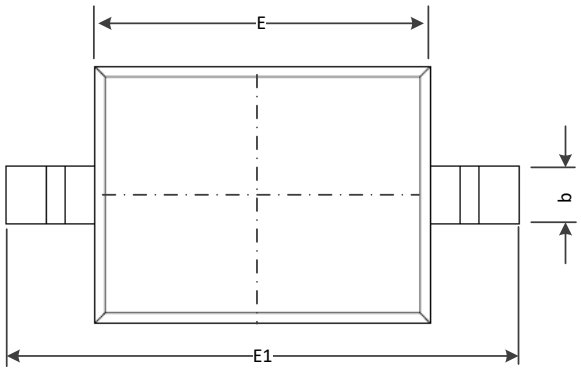


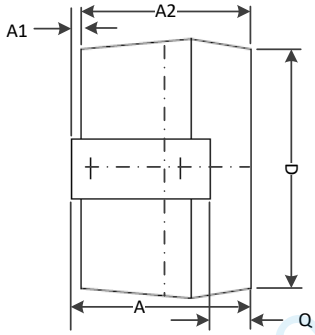
Reverse Clamping Voltage vs. Peak Pulse Current

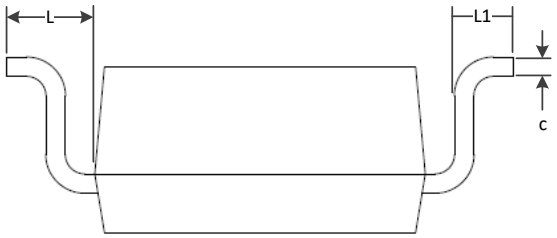


OVREG Semiconductor (Xi'an) Co.,Ltd.

Package information

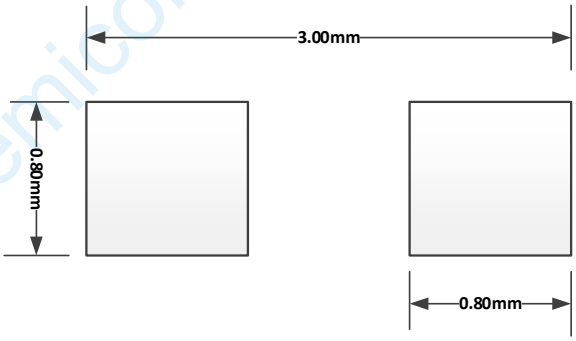






COMMOM DIMENSION (MM)			
PKG	SOD323		
Symbol	MIN.	NOM.	MAX.
A	0.800	0.900	1.000
A1	0.000	0.050	0.100
A2	0.800	0.850	0.900
b	0.250	0.300	0.350
c	0.080	-	0.150
D	1.200	1.300	1.400
E	1.600	1.700	1.800
E1	2.500	2.600	2.700
L	0.475 REF		
L1	0.250	0.260	0.270
Q	0.250 REF		

Recommend PCB Layout



Notes: This PCB Layout Is For Reference Purposes Only

Marking



Ordering Information

Part number	Material	Type	Reel size	MOQ	MOQ/internal box	MOQ/carton
OVE3572W2	GREEN	T/R	7 inch	3k/reel	10reel= 30k/box	4boxes=120k/carton

OVREG Semiconductor (xi'an) Co.,Ltd.